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AOD458

250V,14A N-Channel MOSFET

General Description

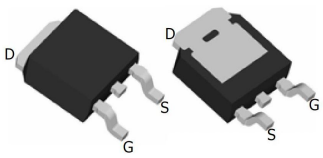
The AOD458 has been fabricated using an advanced high voltage MOSFET process that is designed to deliver high levels of performance and robustness in popular AC-DC applications.By providing low $R_{DS(on)}$, C_{iss} and C_{rss} along with guaranteed avalanche capability this device can be adopted quickly into new and existing offline power supply designs.This device is ideal for boost converters and synchronous rectifiers for consumer, telecom, industrial power supplies and LED backlighting.

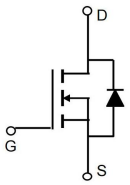
Product Summary

V_{DS}	300V@150℃
I_D (at V_{GS}=10V)	14A
$R_{DS(ON)}$ (at V_{GS}=10V)	<0.28Ω

100% UIS Tested!
100% R_g Tested!

TO252
DPAK





Orderable Part Number	Package Type	Form	Minimum Order Quantity
	TO-252	Tape & Reel	2500

Absolute Maximum Ratings T_A=25°C unless otherwise noted

Parameter		Symbol	Maximum	Units
Drain-Source Voltage		V_{DS}	250	V
Gate-Source Voltage		V_{GS}	±30	V
Continuous Drain Current[B]	T_C=25°C	I_D	14	A
	T_C=100°C		10	
Pulsed Drain Current [C]		I_{DM}	32	
Avalanche Current [C]		I_{AR}	3.4	A
Repetitive avalanche energy [C]		E_{AR}	173	mJ
Single pulsed avalanche energy [H]		E_{AS}	346	mJ
Peak diode recovery dv/dt		dv/dt	5	V/ns
Power Dissipation [B]	T_C=25°C	P_D	150	W
	Derate above 25°C		1	W/ °C
Junction and Storage Temperature Range		T_J, T_{STG}	-50 to 175	°C
Maximum lead temperature for soldering purpose, 1/8" from case for 5 seconds		T_L	300	°C

Thermal Characteristics

Parameter	Symbol	Typical	Maximum	Units
Maximum Junction-to-Ambient [A,G]	$R_{\theta JA}$	45	55	°C/W
Maximum Case-to-sink [A]	$R_{\theta CS}$	-	0.5	°C/W
Maximum Junction-to-Case [D,F]	$R_{\theta JC}$	0.7	1	°C/W

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Electrical Characteristics (T_J=25°C unless otherwise noted)

Symbol	Parameter	Conditions	Min	Typ	Max	Units
STATIC PARAMETERS						
BV_{DSS}	Drain-Source Breakdown Voltage	I_D=250μA, V_{GS}=0V, T_J=25°C	250			V
		I_D=250μA, V_{GS}=0V, T_J=150°C		300		
BV_{DSS} /ΔTJ	Zero Gate Voltage Drain Current	ID=250μA, VGS=0V		0.27		V/°C
I_{DSS}	Zero Gate Voltage Drain Current	V_{DS}=250V, V_{GS}=0V			1	μA
		V_{DS}=200V, T_J=125°C			10	
I_{GSS}	Gate-Body leakage current	V_{DS}=0V, V_{GS}=±30V			±100	nA
$V_{GS(th)}$	Gate Threshold Voltage	V_{DS}=5V, I_D=250μA	3	3.8	4.5	V
$R_{DS(ON)}$	Static Drain-Source On-Resistance	V_{GS}=10V, I_D=7A		0.22	0.28	Ω
g_{FS}	Forward Transconductance	V_{DS}=40V, I_D=7A		10		S
V_{SD}	Diode Forward Voltage	I_S=1A,V_{GS}=0V		0.74	1	V
I_S	Maximum Body-Diode Continuous Current				14	A
I_{SM}	Maximum Body-Diode Pulsed Current				32	A
DYNAMIC PARAMETERS						
C_{iss}	Input Capacitance	V_{GS}=0V, V_{DS}=25V, f=1MHz	505	637	770	pF
C_{oss}	Output Capacitance		70	104	140	pF
C_{rss}	Reverse Transfer Capacitance		3	7.1	12	pF
R_g	Gate resistance	V_{GS}=0V, V_{DS}=0V, f=1MHz	1.3	2.6	3.9	Ω
SWITCHING PARAMETERS						
Q_g	Total Gate Charge	V_{GS}=10V, V_{DS}=200V, I_D=14A	9	12	15	nC
Q_{gs}	Gate Source Charge			3.8		nC
Q_{gd}	Gate Drain Charge			4.6		nC
$t_{D(on)}$	Turn-On DelayTime	V_{GS}=10V, V_{DS}=125V, I_D=14A, R_G=25Ω		21		ns
t_r	Turn-On Rise Time			58		ns
$t_{D(off)}$	Turn-Off DelayTime			29		ns
t_f	Turn-Off Fall Time			33		ns
t_{rr}	Body Diode Reverse Recovery Time	I_F=14A,dI/dt=100A/μs,V_{DS}=100V	120	150	180	ns
Q_{rr}	Body Diode Reverse Recovery Charge	I_F=14A,dI/dt=100A/μs,V_{DS}=100V	1	1.24	1.5	μC

A. The value of $R_{\theta JA}$ is measured with the device in a still air environment with T_A=25°C.

B. The power dissipation P_D is based on $T_{J(MAX)}$=175°C in a TO252 package, using junction-to-case thermal resistance, and is more useful in setting the upper dissipation limit for cases where additional heatsinking is used.

C. Repetitive rating, pulse width limited by junction temperature $T_{J(MAX)}$=175°C.

D. The $R_{\theta JA}$ is the sum of the thermal impedance from junction to case $R_{\theta JC}$ and case to ambient.

E. The static characteristics in Figures 1 to 6 are obtained using <300 μs pulses, duty cycle 0.5% max.

F. These curves are based on the junction-to-case thermal impedance which is measured with the device mounted to a large heatsink, assuming a maximum junction temperature of $T_{J(MAX)}$=175°C.

G.These tests are performed with the device mounted on 1 in^2 FR-4 board with 2oz. Copper, in a still air environment with T_A=25°C.

H. L=60mH, I_{AS}=3.4A, V_{DD}=150V, R_G=10Ω, Starting T_J=25°C

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TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS

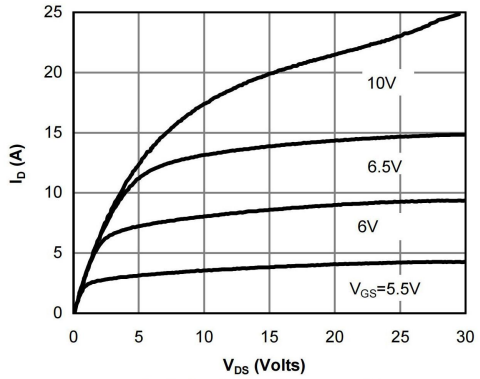


Fig 1: On-Region Characteristics

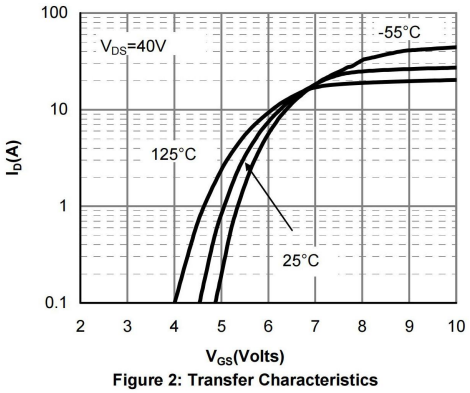


Figure 2: Transfer Characteristics

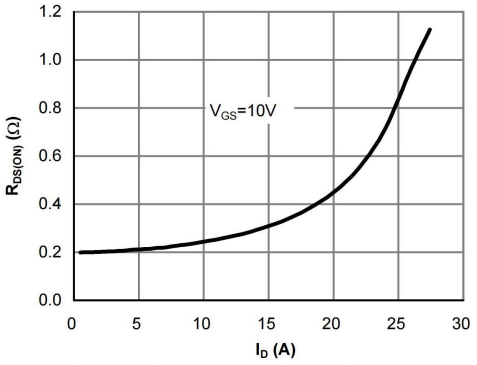


Figure 3: On-Resistance vs. Drain Current and Gate Voltage

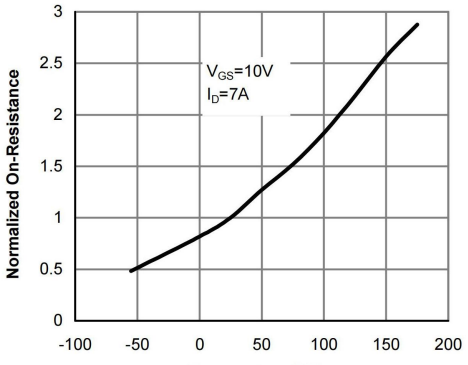


Figure 4: On-Resistance vs. Junction Temperature

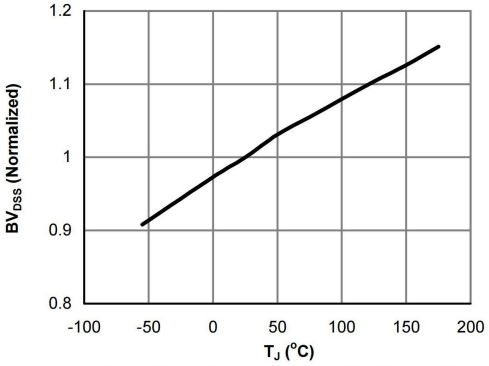


Figure 5: Break Down vs. Junction Temperature

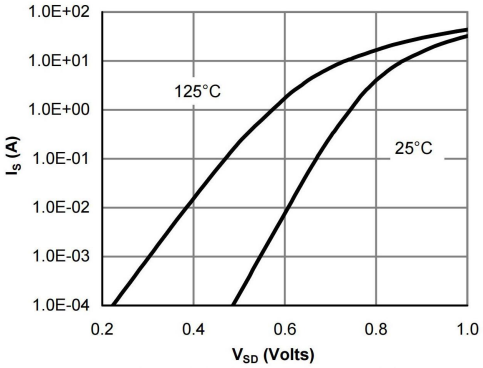


Figure 6: Body-Diode Characteristics

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TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS

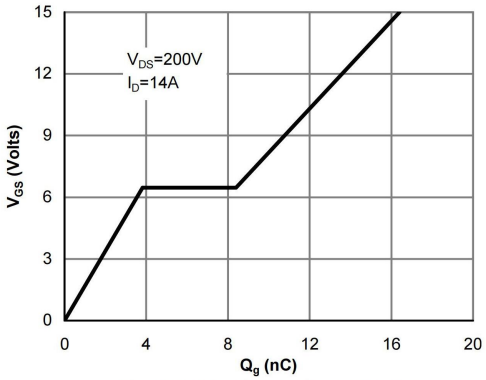


Figure 7: Gate-Charge Characteristics

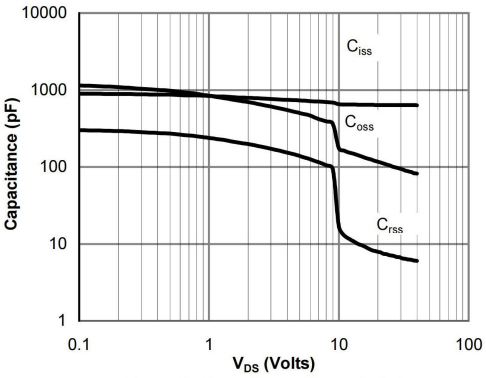


Figure 8: Capacitance Characteristics

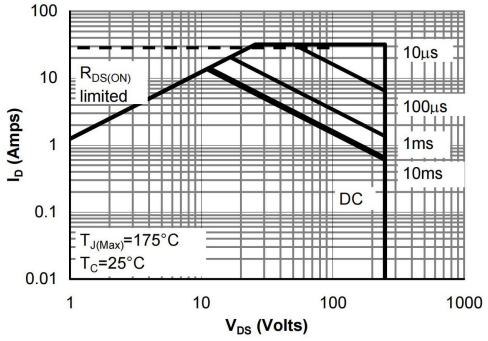


Figure 9: Maximum Forward Biased Safe Operating Area (Note F)

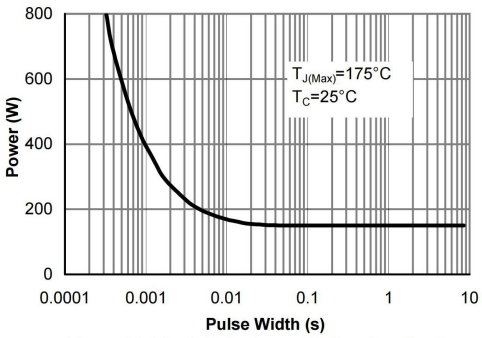


Figure 10: Single Pulse Power Rating Junction-to-Case (Note F)

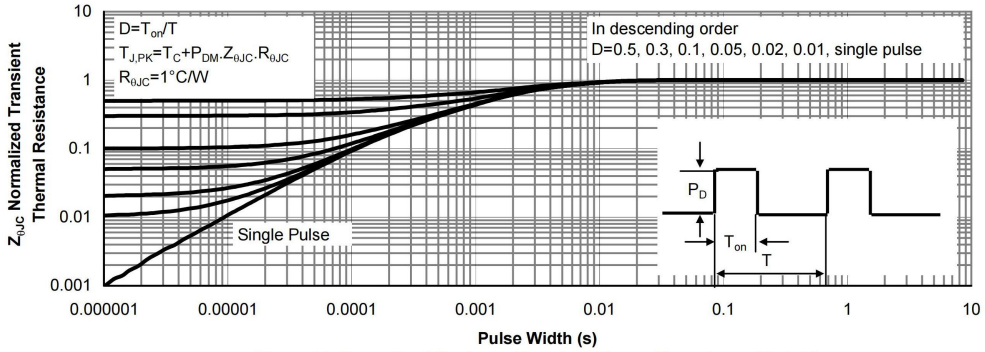


Figure 11: Normalized Maximum Transient Thermal Impedance (Note F)

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TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS

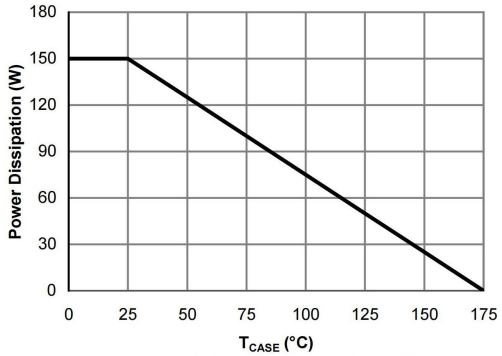


Figure 12: Power De-rating (Note B)

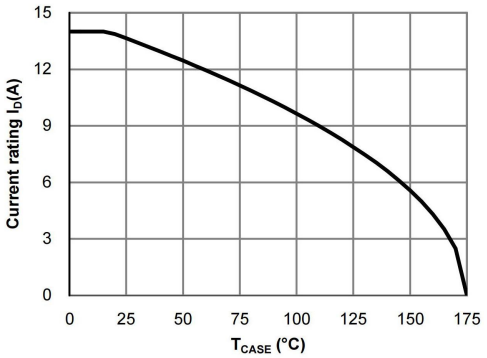


Figure 13: Current De-rating (Note B)

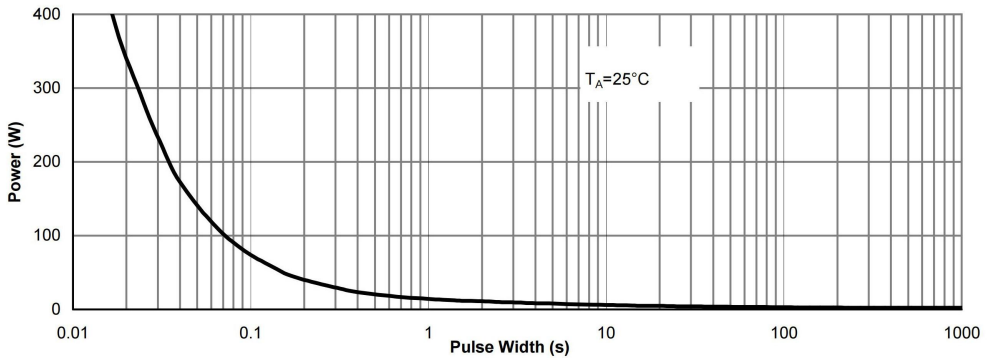


Figure 14: Single Pulse Power Rating Junction-to-Ambient (Note G)

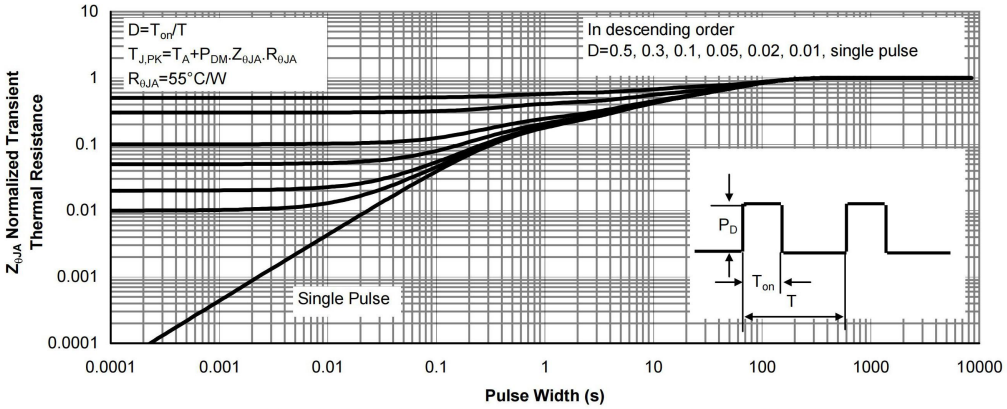
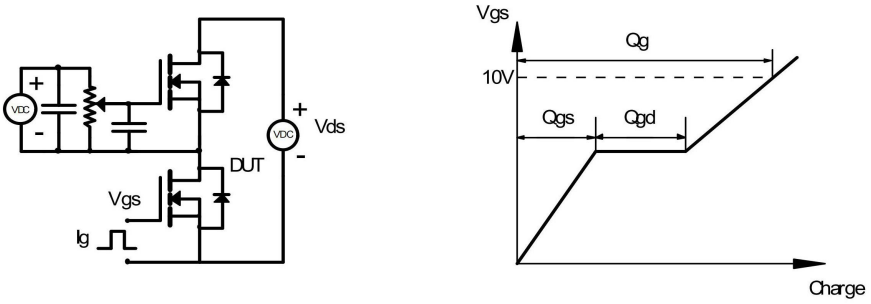


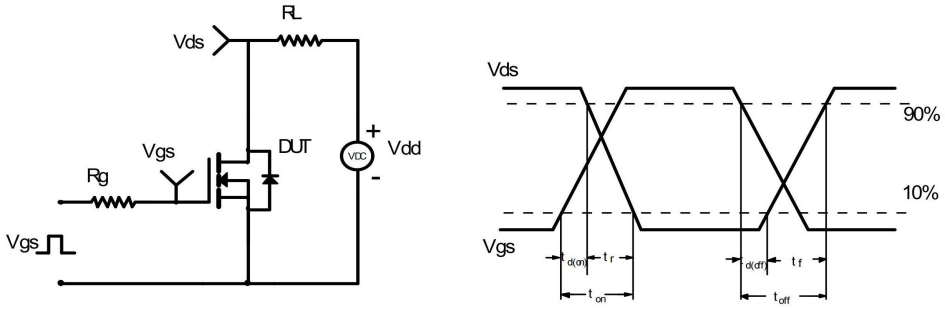
Figure 15: Normalized Maximum Transient Thermal Impedance (Note G)

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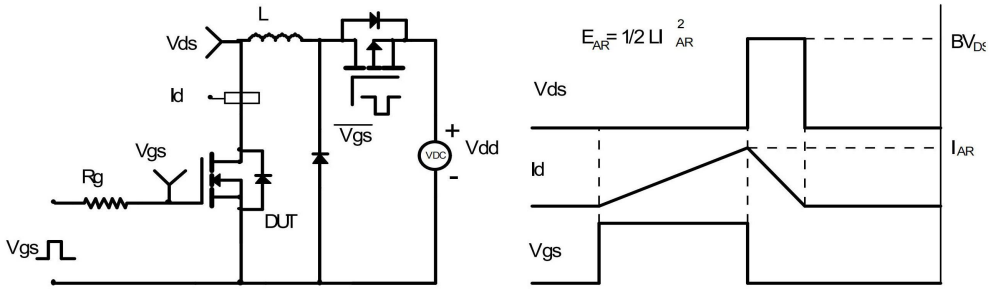
Gate Charge Test Circuit & Waveform



Resistive Switching Test Circuit & Waveforms



Unclamped Inductive Switching (UIS) Test Circuit & Waveforms



Diode Recovery Test Circuit & Waveforms

